Features

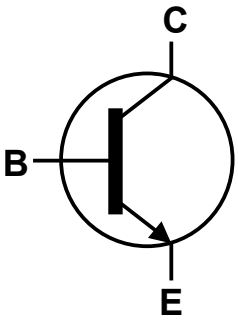
- Epitaxial Planar Die Construction
- Ideal for Low Power Amplification and Switching
- Complementary PNP Type: MMBTA55 & MMBTA56
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP capable (Note 4)**

Mechanical Data

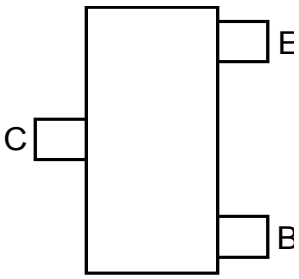
- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 e3
- Weight: 0.008 grams (approximate)

SOT23

Top View



Device Symbol



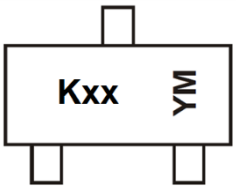
Top View
Pin Configuration

Ordering Information (Notes 4 & 5)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
MMBTA05-7-F	AEC-Q101	K1G / K1H	7	8	3,000
MMBTA05Q-13-F	Automotive	K1G / K1H	13	8	10,000
MMBTA06-7-F	AEC-Q101	K1G	7	8	3,000
MMBTA06Q-7-F	Automotive	K1G	7	8	3,000

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_compliance_definitions/.
5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



Kxx = Product Type Marking Code (See Ordering Information)
YM = Date Code Marking
Y or $\overline{Y}$ = Year (ex: A = 2013)
M or $\overline{M}$ = Month (ex: 9 = September)

Date Code Key

Year	2010	2011	2012	2013	2014	2015	2016	2017
Code	X	Y	Z	A	B	C	D	E

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	MMBTA05	MMBTA06	Unit
Collector-Base Voltage	V_{CBO}	60	80	V
Collector-Emitter Voltage	V_{CEO}	60	80	V
Emitter-Base Voltage	V_{EBO}	4.0		V
Collector Current	I_C	500		mA
Peak Collector Current	I_{CM}	1		A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

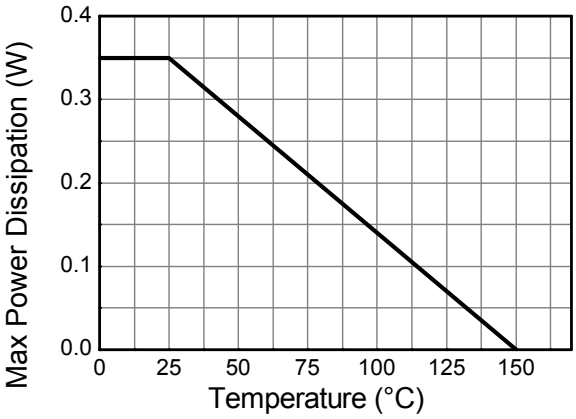
Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 6)	P_D	310	mW
	(Note 7)		350	
Thermal Resistance, Junction to Ambient	(Note 6)	$R_{\theta JA}$	403	°C/W
	(Note 7)		357	
Thermal Resistance, Junction to Leads	(Note 8)	$R_{\theta JL}$	350	°C/W
Operating and Storage Temperature Range		T_J,T_{STG}	-55 to +150	°C

ESD Ratings (Note 9)

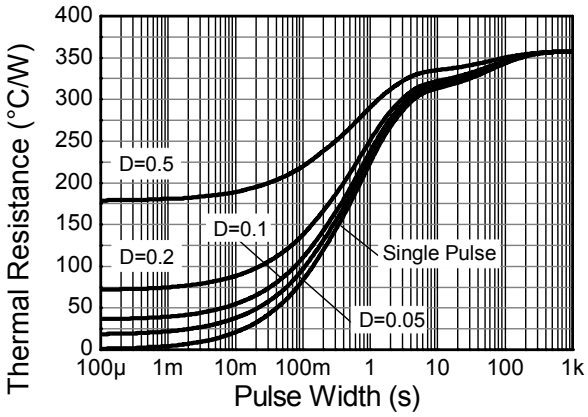
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

Notes:
6. For a device mounted on minimum recommended pad layout 1oz copper that is on a single-sided FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
7. Same as note (6), except the device is mounted on 15 mm x 15mm 1oz copper.
8. Thermal resistance from junction to solder-point (at the end of the leads).
9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

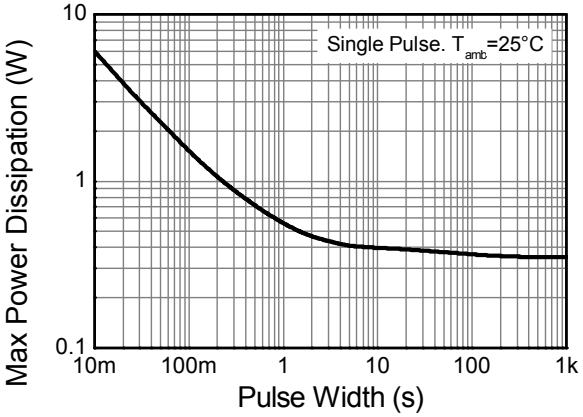
Thermal Characteristics and Derating Information



Derating Curve



Transient Thermal Impedance



Pulse Power Dissipation

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	MMBTA05 MMBTA06	BV_{CBO}	60 80	—	V	I_C = 100μA, I_E = 0
Collector-Emitter Breakdown Voltage (Note 10)	MMBTA05 MMBTA06	BV_{CEO}	60 80	—	V	I_C = 10.0mA, I_B = 0
Emitter-Base Breakdown Voltage		BV_{EBO}	4.0	—	V	I_E = 100 μA, I_C = 0
Collector Cutoff Current	MMBTA05 MMBTA06	I_{CBO}	—	100	nA	V_{CB} = 60V, I_E = 0 V_{CB} = 80V, I_E = 0
Collector Cutoff Current	MMBTA05 MMBTA06	I_{CES}	—	100	nA	V_{CE} = 60V, I_{BO} = 0V V_{CE} = 80V, I_{BO} = 0V
ON CHARACTERISTICS (Note 10)						
DC Current Gain		h_{FE}	100	—	—	I_C = 10mA, V_{CE} = 1.0V I_C = 100mA, V_{CE} = 1.0V
Collector-Emitter Saturation Voltage		$V_{CE(sat)}$	—	0.25	V	I_C = 100mA, I_B = 10mA
Base-Emitter Saturation Voltage		$V_{BE(sat)}$	—	1.2	V	I_C = 100mA, V_{CE} = 1.0V
SMALL SIGNAL CHARACTERISTICS						
Current Gain-Bandwidth Product		f_T	100	—	MHz	V_{CE} = 2.0V, I_C = 10mA, f = 100MHz

Note: 10. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

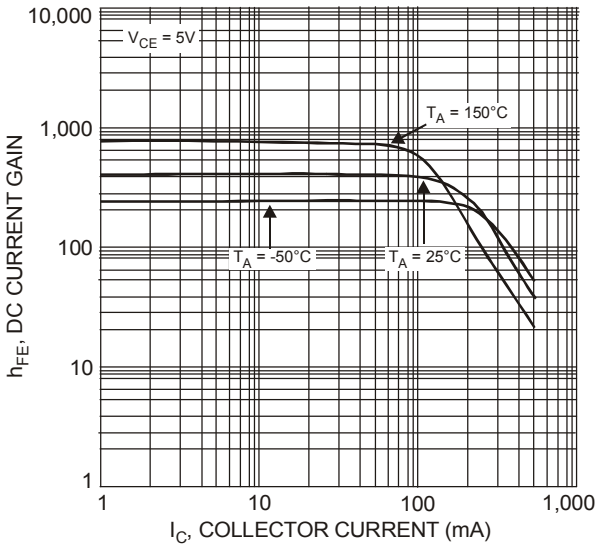


Figure 1 Typical DC Current Gain vs. Collector Current

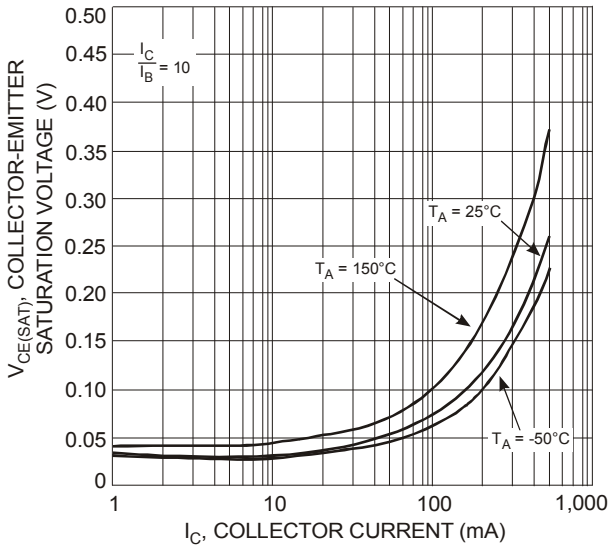


Figure 2 Collector-Emitter Saturation Voltage vs. Collector Current

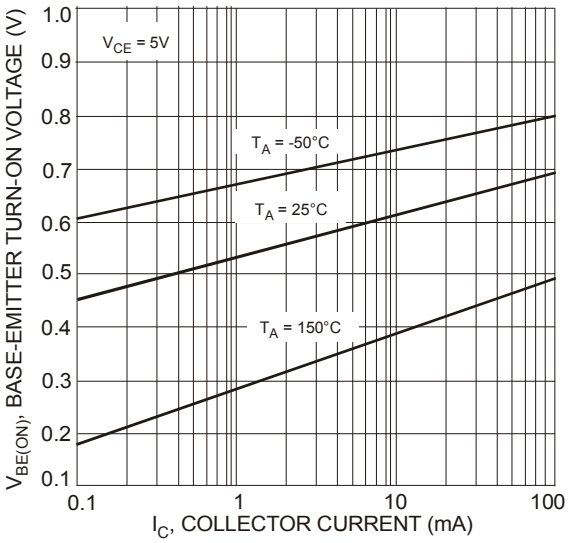


Figure 3 Typical Base-Emitter Turn-On Voltage vs. Collector Current

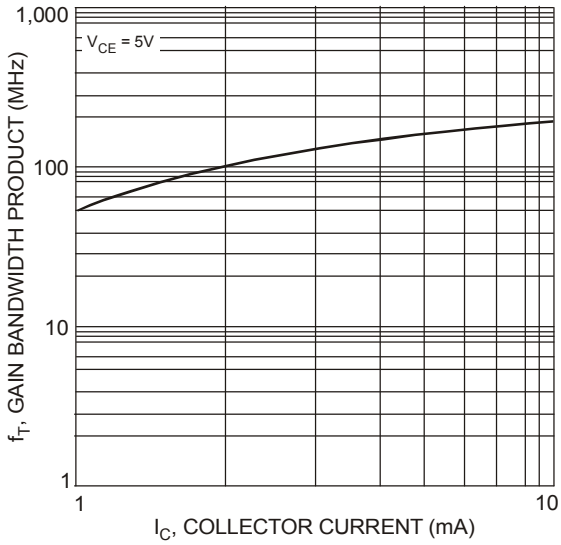


Figure 4 Typical Gain Bandwidth Product vs. Collector Current

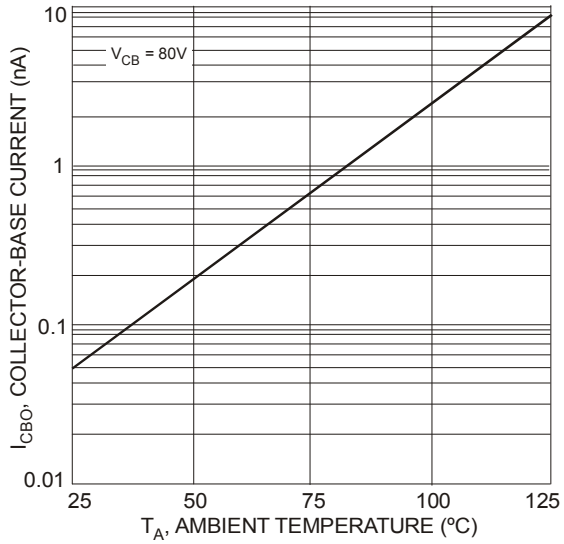


Figure 5 Typical Collector-Cutoff Current vs. Ambient Temperature

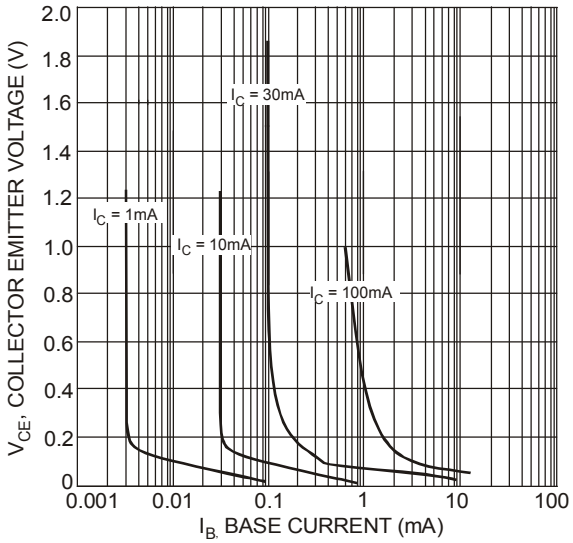
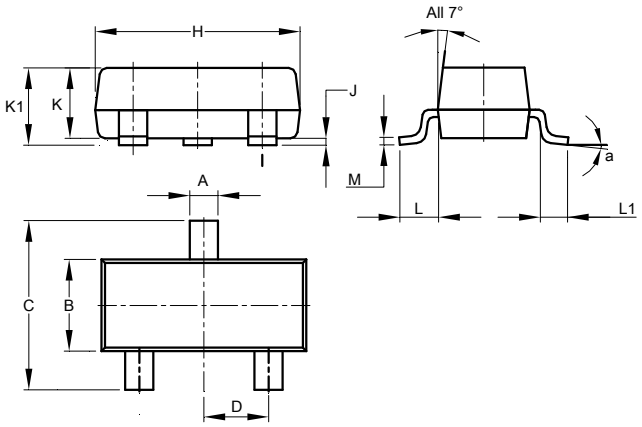


Figure 6 Typical Collector Saturation Region

Package Outline Dimensions

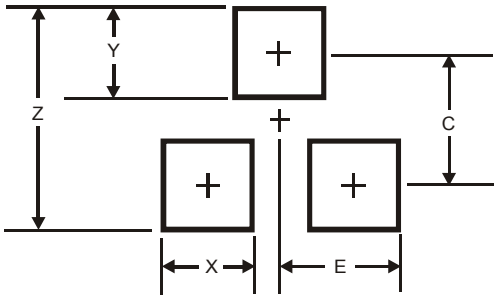
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT23			
Dim	**Min**	**Max**	**Typ**
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	8°		
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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